



Welcome to E-XFL.COM

#### What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

#### Applications of "<u>Embedded -</u> <u>Microcontrollers</u>"

#### Details

Product Status	Active
Core Processor	ARM® Cortex®-M4/M0
Core Size	32-Bit Dual-Core
Speed	204MHz
Connectivity	CANbus, EBI/EMI, Ethernet, I <sup>2</sup> C, IrDA, Microwire, SD, SPI, SSI, SSP, UART/USART, USB, USB OTG
Peripherals	Brown-out Detect/Reset, DMA, I <sup>2</sup> S, Motor Control PWM, POR, PWM, WDT
Number of I/O	83
Program Memory Size	1MB (1M x 8)
Program Memory Type	FLASH
EEPROM Size	16K x 8
RAM Size	136K x 8
Voltage - Supply (Vcc/Vdd)	2.2V ~ 3.6V
Data Converters	A/D 8x10b; D/A 1x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 105°C (TA)
Mounting Type	Surface Mount
Package / Case	144-LQFP
Supplier Device Package	144-LQFP (20x20)
Purchase URL	https://www.e-xfl.com/product-detail/nxp-semiconductors/lpc4337jbd144e

Email: info@E-XFL.COM

Address: Room A, 16/F, Full Win Commercial Centre, 573 Nathan Road, Mongkok, Hong Kong

## **NXP Semiconductors**

# LPC435x/3x/2x/1x

## 32-bit ARM Cortex-M4/M0 microcontroller

### Table 3.Pin description

Pin name	256	A100	803	44		state		Description
	BGA	FBG/	QFP2	QFP1		teset <u> </u> ]	ype	
Multiplexed dig	∣⊐ ital pin	∣⊢ IS					F	
P0 0	L3	G2	47	32	[2]	N:	I/O	GPI00[0] — General purpose digital input/output pin.
_						ΡÛ	I/O	SSP1_MISO — Master In Slave Out for SSP1.
							I	ENET_RXD1 — Ethernet receive data 1 (RMII/MII interface).
							I/O	SGPI00 — General purpose digital input/output pin.
							-	R — Function reserved.
							-	R — Function reserved.
	I/O <b>I2S0_TX_WS</b> master and re WS in the <i>PS</i>		<b>I2S0_TX_WS</b> — Transmit Word Select. It is driven by the master and received by the slave. Corresponds to the signal WS in the <i>I</i> <sup>2</sup> S-bus specification.					
							I/O	<b>I2S1_TX_WS</b> — Transmit Word Select. It is driven by the master and received by the slave. Corresponds to the signal WS in the <i>PS-bus specification</i> .
P0_1	M2	G1	50	34	[2]	N;	I/O	GPIO0[1] — General purpose digital input/output pin.
						PU	I/O	SSP1_MOSI — Master Out Slave in for SSP1.
							I	<b>ENET_COL</b> — Ethernet Collision detect (MII interface).
							I/O	<b>SGPIO1</b> — General purpose digital input/output pin.
							-	R — Function reserved.
							-	R — Function reserved.
								<b>ENET_TX_EN</b> — Ethernet transmit enable (RMII/MII interface).
							I/O	<b>I2S1_TX_SDA</b> — I2S1 transmit data. It is driven by the transmitter and read by the receiver. Corresponds to the signal SD in the $l^2S$ -bus specification.
P1_0	P2	H1	54	38	[2]	N;	I/O	GPIO0[4] — General purpose digital input/output pin.
						PU	I	<b>CTIN_3</b> — SCT input 3. Capture input 1 of timer 1.
							I/O	<b>EMC_A5</b> — External memory address line 5.
							-	R — Function reserved.
							-	R — Function reserved.
							I/O	SSP0_SSEL — Slave Select for SSP0.
							I/O	SGPI07 — General purpose digital input/output pin.
							I/O	<b>EMC_D12</b> — External memory data line 12.

Pin name	LBGA256	TFBGA100	LQFP208	LQFP144		Reset state [1]	Type	Description
P1_20	M10	K10	100	70	[2]	N;	I/O	GPIO0[15] — General purpose digital input/output pin.
						PU	I/O	SSP1_SSEL — Slave Select for SSP1.
							-	R — Function reserved.
							0	<b>ENET_TXD1</b> — Ethernet transmit data 1 (RMII/MII interface).
							I	T0_CAP2 — Capture input 2 of timer 0.
							-	R — Function reserved.
							I/O	SGPI013 — General purpose digital input/output pin.
							I/O	EMC_D11 — External memory data line 11.
P2_0	T16	G10	108	75	[2]	N;	I/O	SGPIO4 — General purpose digital input/output pin.
						PU	0	<b>U0_TXD</b> — Transmitter output for USART0. See <u>Table 4</u> for ISP mode.
							I/O	EMC_A13 — External memory address line 13.
							0	<b>USB0_PPWR</b> — VBUS drive signal (towards external charge pump or power management unit); indicates that VBUS must be driven (active HIGH).
						Add a pul This sign: USB_PP		Add a pull-down resistor to disable the power switch at reset. This signal has opposite polarity compared to the USB_PPWR used on other NXP LPC parts.
							I/O	GPIO5[0] — General purpose digital input/output pin.
							-	R — Function reserved.
							I	T3_CAP0 — Capture input 0 of timer 3.
							0	ENET_MDC — Ethernet MIIM clock.
P2_1	N15	G7	116	81	[2]	N;	I/O	SGPI05 — General purpose digital input/output pin.
						PU	I	<b>U0_RXD</b> — Receiver input for USART0. See <u>Table 4</u> for ISP mode.
							I/O	EMC_A12 — External memory address line 12.
							I	<b>USB0_PWR_FAULT</b> — Port power fault signal indicating overcurrent condition; this signal monitors over-current on the USB bus (external circuitry required to detect over-current condition).
							I/O	GPIO5[1] — General purpose digital input/output pin.
							-	R — Function reserved.
							I	T3_CAP1 — Capture input 1 of timer 3.
							-	R — Function reserved.

 Table 3.
 Pin description ...continued

Pin name	LBGA256	TFBGA100	LQFP208	LQFP144		Reset state	Type	Description
P2_9	H16	B10	144	102	[2]	N; PU	I/O	<b>GPIO1[10]</b> — General purpose digital input/output pin. Boot pin (see <u>Table 5</u> ).
							0	<b>CTOUT_3</b> — SCT output 3. Match output 3 of timer 0.
							I/O	U3_BAUD — Baud pin for USART3.
							I/O	<b>EMC_A0</b> — External memory address line 0.
							-	R — Function reserved.
							-	R — Function reserved.
							-	R — Function reserved.
							-	R — Function reserved.
P2_10	G16	E8	146	104	[2]	N;	I/O	<b>GPIO0[14]</b> — General purpose digital input/output pin.
						PU	0	<b>CTOUT_2</b> — SCT output 2. Match output 2 of timer 0.
							0	<b>U2_TXD</b> — Transmitter output for USART2.
							I/O	<b>EMC_A1</b> — External memory address line 1.
							-	R — Function reserved.
							-	R — Function reserved.
							-	R — Function reserved.
							-	R — Function reserved.
P2_11	F16	A9	148	105	[2]	N;	I/O	<b>GPIO1[11]</b> — General purpose digital input/output pin.
						PU	0	<b>CTOUT_5</b> — SCT output 5. Match output 3 of timer 3.
							I	U2_RXD — Receiver input for USART2.
							I/O	<b>EMC_A2</b> — External memory address line 2.
							-	R — Function reserved.
							-	R — Function reserved.
							-	R — Function reserved.
							-	R — Function reserved.
P2_12	E15	B9	153	106	<u>[2]</u>	N;	I/O	<b>GPIO1[12]</b> — General purpose digital input/output pin.
						PU	0	<b>CTOUT_4</b> — SCT output 4. Match output 3 of timer 3.
							-	R — Function reserved.
							I/O	EMC_A3 — External memory address line 3.
							-	R — Function reserved.
							-	R — Function reserved.
							-	R — Function reserved.
							I/O	<b>U2_UCLK</b> — Serial clock input/output for USART2 in synchronous mode.

 Table 3.
 Pin description ...continued

Pin name	BGA256	FBGA100	QFP208	QFP144		teset state	ype	Description
PD 3	P4	-	-	-	[2]	N:	-	<b>R</b> — Function reserved.
						PU	0	<b>CTOUT 6</b> —SCT output 7. Match output 2 of timer 1.
							I/O	EMC D17 — External memory data line 17.
							-	R — Function reserved.
							I/O	GPIO6[17] — General purpose digital input/output pin.
							-	R — Function reserved.
							-	R — Function reserved.
							I/O	SGPI07 — General purpose digital input/output pin.
PD_4	T2	-	-	-	[2]	N;	-	R — Function reserved.
						PU	0	CTOUT_8 — SCT output 8. Match output 0 of timer 2.
							I/O	EMC_D18 — External memory data line 18.
							-	R — Function reserved.
							I/O	GPIO6[18] — General purpose digital input/output pin.
							-	R — Function reserved.
							-	R — Function reserved.
							I/O	SGPIO8 — General purpose digital input/output pin.
PD_5	P6	-	-	-	[2]	N;	-	R — Function reserved.
						PU	0	<b>CTOUT_9</b> — SCT output 9. Match output 3 of timer 3.
							I/O	EMC_D19 — External memory data line 19.
							-	R — Function reserved.
							I/O	<b>GPIO6[19]</b> — General purpose digital input/output pin.
							-	R — Function reserved.
							-	R — Function reserved.
							I/O	<b>SGPIO9</b> — General purpose digital input/output pin.
PD_6	R6	-	68	-	[2]	N; DU	-	R — Function reserved.
						FU	0	<b>CTOUT_10</b> — SCT output 10. Match output 3 of timer 3.
							I/O	EMC_D20 — External memory data line 20.
							-	R — Function reserved.
							I/O	<b>GPIO6[20]</b> — General purpose digital input/output pin.
							-	R — Function reserved.
							-	R — Function reserved.
							I/O	SGPI010 — General purpose digital input/output pin.

 Table 3.
 Pin description ...continued

Pin name	LBGA256	TFBGA100	LQFP208	LQFP144		Reset state	Type	Description
PE_2	M14	-	115	-	[2]	N;	I	ADCTRIG0 — ADC trigger input 0.
						PU	I	CAN0_RD — CAN receiver input.
							-	R — Function reserved.
							I/O	<b>EMC_A20</b> — External memory address line 20.
							I/O	<b>GPI07[2]</b> — General purpose digital input/output pin.
							-	R — Function reserved.
							-	R — Function reserved.
							-	R — Function reserved.
PE_3	K12	-	118	-	[2]	N;	-	R — Function reserved.
						PU	0	<b>CAN0_TD</b> — CAN transmitter output.
							I	ADCTRIG1 — ADC trigger input 1.
							I/O	<b>EMC_A21</b> — External memory address line 21.
							I/O	GPI07[3] — General purpose digital input/output pin.
							-	R — Function reserved.
							-	R — Function reserved.
							-	R — Function reserved.
PE_4	K13	-	120	-	[2]	N;	-	R — Function reserved.
						PU	I	<b>NMI</b> — External interrupt input to NMI.
							-	R — Function reserved.
							I/O	<b>EMC_A22</b> — External memory address line 22.
							I/O	<b>GPI07[4]</b> — General purpose digital input/output pin.
							-	R — Function reserved.
							-	R — Function reserved.
							-	R — Function reserved.
PE_5	N16	-	122	-	[2]	N;	-	R — Function reserved.
						FU	0	<b>CTOUT_3</b> — SCT output 3. Match output 3 of timer 0.
							0	<b>U1_RTS</b> — Request to Send output for UART 1. Can also be configured to be an RS-485/EIA-485 output enable signal for UART 1.
							I/O	EMC_D24 — External memory data line 24.
							I/O	<b>GPIO7[5]</b> — General purpose digital input/output pin.
							-	R — Function reserved.
							-	R — Function reserved.
							-	R — Function reserved.

 Table 3.
 Pin description ...continued

Pin name	LBGA256	TFBGA100	LQFP208	LQFP144		Reset state	Type	Description
PE_10	E14	-	154	-	[2]	N;	-	R — Function reserved.
						PU	I	CTIN_3 — SCT input 3. Capture input 1 of timer 1.
							0	<b>U1_DTR</b> — Data Terminal Ready output for UART 1. Can also be configured to be an RS-485/EIA-485 output enable signal for UART 1.
							I/O	EMC_D29 — External memory data line 29.
							I/O	<b>GPIO7[10]</b> — General purpose digital input/output pin.
							-	R — Function reserved.
							-	R — Function reserved.
							-	R — Function reserved.
PE_11	D16	-	-	-	[2]	N;	-	R — Function reserved.
						PU	0	CTOUT_12 — SCT output 12. Match output 3 of timer 3.
							0	U1_TXD — Transmitter output for UART 1.
							I/O	EMC_D30 — External memory data line 30.
							I/O	GPI07[11] — General purpose digital input/output pin.
							-	R — Function reserved.
							-	R — Function reserved.
							-	R — Function reserved.
PE_12	D15	-	-	-	[2]	N;	-	R — Function reserved.
						PU	0	<b>CTOUT_11</b> — SCT output 11. Match output 3 of timer 2.
							I	<b>U1_RXD</b> — Receiver input for UART 1.
							I/O	EMC_D31 — External memory data line 31.
							I/O	GPI07[12] — General purpose digital input/output pin.
							-	R — Function reserved.
							-	R — Function reserved.
							-	R — Function reserved.
PE_13	G14	-	-	-	[2]	N;	-	R — Function reserved.
						PU	0	<b>CTOUT_14</b> — SCT output 14. Match output 2 of timer 3.
							I/O	<b>I2C1_SDA</b> — I <sup>2</sup> C1 data input/output (this pin does not use a specialized I2C pad).
							0	<b>EMC_DQMOUT3</b> — Data mask 3 used with SDRAM and static devices.
							I/O	GPIO7[13] — General purpose digital input/output pin.
							-	R — Function reserved.
							-	R — Function reserved.
							-	R — Function reserved.

 Table 3.
 Pin description ...continued

32-bit ARM Cortex-M4/M0 microcontroller

## 7.15 One-Time Programmable (OTP) memory

The OTP provides 64 bit+ 256 bit of memory for general-purpose use.

## 7.16 General Purpose I/O (GPIO)

The LPC435x/3x/2x/1x provide eight GPIO ports with up to 31 GPIO pins each.

Device pins that are not connected to a specific peripheral function are controlled by the GPIO registers. Pins may be dynamically configured as inputs or outputs. Separate registers allow setting or clearing any number of outputs simultaneously. The value of the output register may be read back as well as the current state of the port pins.

All GPIO pins default to inputs with pull-up resistors enabled and input buffer disabled on reset. The input buffer must be turned on in the system control block SFS register before the GPIO input can be read.

## 7.16.1 Features

- Accelerated GPIO functions:
  - GPIO registers are located on the AHB so that the fastest possible I/O timing can be achieved.
  - Mask registers allow treating sets of port bits as a group, leaving other bits unchanged.
  - All GPIO registers are byte and half-word addressable.
  - Entire port value can be written in one instruction.
- Bit-level set and clear registers allow a single instruction set or clear of any number of bits in one port.
- Direction control of individual bits.
- Up to eight GPIO pins can be selected from all GPIO pins to create an edge- or level-sensitive GPIO interrupt request (GPIO interrupts).
- Two GPIO group interrupts can be triggered by any pin or pins in each port (GPIO group0 and group1 interrupts).

## 7.17 Configurable digital peripherals

## 7.17.1 State Configurable Timer (SCTimer/PWM) subsystem

The SCTimer/PWM allows a wide variety of timing, counting, output modulation, and input capture operations. The inputs and outputs of the SCTimer/PWM are shared with the capture and match inputs/outputs of the 32-bit general purpose counter/timers.

The SCTimer/PWM can be configured as two 16-bit counters or a unified 32-bit counter. In the two-counter case, in addition to the counter value the following operational elements are independent for each half:

- State variable
- Limit, halt, stop, and start conditions
- Values of Match/Capture registers, plus reload or capture control values

LPC435X 3X 2X 1X

### 32-bit ARM Cortex-M4/M0 microcontroller

In the two-counter case, the following operational elements are global to the SCTimer/PWM, but the last three can use match conditions from either counter:

- Clock selection
- Inputs
- Events
- Outputs
- Interrupts

### 7.17.1.1 Features

- Two 16-bit counters or one 32-bit counter.
- · Counters clocked by bus clock or selected input.
- Up counters or up-down counters.
- State variable allows sequencing across multiple counter cycles.
- The following conditions define an event: a counter match condition, an input (or output) condition, a combination of a match and/or and input/output condition in a specified state.
- Events control outputs, interrupts, and DMA requests.
  - Match register 0 can be used as an automatic limit.
  - In bi-directional mode, events can be enabled based on the count direction.
  - Match events can be held until another qualifying event occurs.
- Selected events can limit, halt, start, or stop a counter.
- Supports:
  - 8 inputs
  - 16 outputs
  - 16 match/capture registers
  - 16 events
  - 32 states
  - Match register 0 to 5 support a fractional component for the dither engine

### 7.17.2 Serial GPIO (SGPIO)

The Serial GPIOs offer standard GPIO functionality enhanced with features to accelerate serial stream processing.

### 7.17.2.1 Features

- Each SGPIO input/output slice can be used to perform a serial to parallel or parallel to serial data conversion.
- 16 SGPIO input/output slices each with a 32-bit FIFO that can shift the input value from a pin or an output value to a pin with every cycle of a shift clock.
- Each slice is double-buffered.
- Interrupt is generated on a full FIFO, shift clock, or pattern match.
- Slices can be concatenated to increase buffer size.

### 32-bit ARM Cortex-M4/M0 microcontroller

• Each slice has a 32-bit pattern match filter.

## 7.18 AHB peripherals

### 7.18.1 General Purpose DMA

The DMA controller allows peripheral-to memory, memory-to-peripheral, peripheral-to-peripheral, and memory-to-memory transactions. Each DMA stream provides unidirectional serial DMA transfers for a single source and destination. For example, a bidirectional port requires one stream for transmit and one for receives. The source and destination areas can each be either a memory region or a peripheral for master 1, but only memory for master 0.

### 7.18.1.1 Features

- Eight DMA channels. Each channel can support a unidirectional transfer.
- 16 DMA request lines.
- Single DMA and burst DMA request signals. Each peripheral connected to the DMA Controller can assert either a burst DMA request or a single DMA request. The DMA burst size is set by programming the DMA Controller.
- Memory-to-memory, memory-to-peripheral, peripheral-to-memory, and peripheral-to-peripheral transfers are supported.
- Scatter or gather DMA is supported through the use of linked lists. This means that the source and destination areas do not have to occupy contiguous areas of memory.
- Hardware DMA channel priority.
- AHB slave DMA programming interface. The DMA Controller is programmed by writing to the DMA control registers over the AHB slave interface.
- Two AHB bus masters for transferring data. These interfaces transfer data when a DMA request goes active. Master 1 can access memories and peripherals, master 0 can access memories only.
- 32-bit AHB master bus width.
- Incrementing or non-incrementing addressing for source and destination.
- Programmable DMA burst size. The DMA burst size can be programmed to more efficiently transfer data.
- Internal four-word FIFO per channel.
- Supports 8, 16, and 32-bit wide transactions.
- Big-endian and little-endian support. The DMA Controller defaults to little-endian mode on reset.
- An interrupt to the processor can be generated on a DMA completion or when a DMA error has occurred.
- Raw interrupt status. The DMA error and DMA count raw interrupt status can be read prior to masking.

## 7.18.2 SPI Flash Interface (SPIFI)

The SPI Flash Interface allows low-cost serial flash memories to be connected to the ARM Cortex-M4 processor with little performance penalty compared to parallel flash devices with higher pin count.

### 32-bit ARM Cortex-M4/M0 microcontroller

### 7.18.5 High-speed USB Host/Device/OTG interface (USB0)

**Remark:** USB0 is available on the following parts: LPC435x, LPC433x, LPC432x. USB0 is not available on the LPC431x parts.

The USB OTG module allows the LPC435x/3x/2x/1x to connect directly to a USB Host such as a PC (in device mode) or to a USB Device in host mode.

### 7.18.5.1 Features

- Contains UTMI+ compliant high-speed transceiver (PHY).
- Complies with Universal Serial Bus specification 2.0.
- Complies with USB On-The-Go supplement.
- Complies with Enhanced Host Controller Interface Specification.
- Supports auto USB 2.0 mode discovery.
- Supports all high-speed USB-compliant peripherals.
- Supports all full-speed USB-compliant peripherals.
- Supports software Host Negotiation Protocol (HNP) and Session Request Protocol (SRP) for OTG peripherals.
- Supports interrupts.
- Supports Start Of Frame (SOF) frame length adjust.
- This module has its own, integrated DMA engine.
- USB interface electrical test software included in ROM USB stack.

### 7.18.6 High-speed USB Host/Device interface with ULPI (USB1)

**Remark:** USB1 is available on the following parts: LPC435x and LPC433x. USB1 is not available on the LPC432x and LPC431x parts.

The USB1 interface can operate as a full-speed USB Host/Device interface or can connect to an external ULPI PHY for High-speed operation.

#### 7.18.6.1 Features

- Complies with Universal Serial Bus specification 2.0.
- Complies with Enhanced Host Controller Interface Specification.
- Supports auto USB 2.0 mode discovery.
- Supports all high-speed USB-compliant peripherals if connected to external ULPI PHY.
- Supports all full-speed USB-compliant peripherals.
- Supports interrupts.
- Supports Start Of Frame (SOF) frame length adjust.
- This module has its own, integrated DMA engine.
- USB interface electrical test software included in ROM USB stack.

### 7.18.7 LCD controller

**Remark:** The LCD controller is only available on parts LPC435x. LCD is not available on parts LPC433x, LPC432x, and LPC431x.

LPC435X 3X 2X 1X

© NXP Semiconductors N.V. 2016. All rights reserved.

### 32-bit ARM Cortex-M4/M0 microcontroller

### 7.19.6.1 Features

- The I<sup>2</sup>S interfaces has separate input/output channels, each of which can operate in master or slave mode.
- Capable of handling 8-bit, 16-bit, and 32-bit word sizes.
- Mono and stereo audio data supported.
- The sampling frequency can range from 16 kHz to 192 kHz (16, 22.05, 32, 44.1, 48, 96, 192) kHz.
- Support for an audio master clock.
- Configurable word select period in master mode (separately for I<sup>2</sup>S-bus input and output).
- Two 8-word FIFO data buffers are provided, one for transmit and one for receive.
- Generates interrupt requests when buffer levels cross a programmable boundary.
- Two DMA requests controlled by programmable buffer levels. The DMA requests are connected to the GPDMA block.
- Controls include reset, stop and mute options separately for I<sup>2</sup>S-bus input and I<sup>2</sup>S-bus output.

## 7.19.7 C\_CAN

**Remark:** The LPC435x/3x/2x/1x each contain two C\_CAN controllers.

Controller Area Network (CAN) is the definition of a high performance communication protocol for serial data communication. The C\_CAN controller is designed to provide a full implementation of the CAN protocol according to the CAN Specification Version 2.0B. The C\_CAN controller allows to build powerful local networks with low-cost multiplex wiring by supporting distributed real-time control with a high level of reliability.

### 7.19.7.1 Features

- Conforms to protocol version 2.0 parts A and B.
- Supports bit rate of up to 1 Mbit/s.
- Supports 32 Message Objects.
- Each Message Object has its own identifier mask.
- Provides programmable FIFO mode (concatenation of Message Objects).
- Provides maskable interrupts.
- Supports Disabled Automatic Retransmission (DAR) mode for time-triggered CAN applications.
- Provides programmable loop-back mode for self-test operation.

## 7.20 Counter/timers and motor control

### 7.20.1 General purpose 32-bit timers/external event counters

**Remark:** The LPC435x/3x/2x/1x include four 32-bit timer/counters.

### 32-bit ARM Cortex-M4/M0 microcontroller

Symbol	Parameter	Conditions		Min	Typ[1]	Max	Unit
V <sub>IC</sub>	common-mode input	high-speed mode		-50	200	500	mV
	voltage	full-speed/low-speed mode		800	-	2500	mV
		chirp mode		-50	-	600	mV
V <sub>i(dif)</sub>	differential input voltage			100	400	1100	mV
USB1 pins (	USB1_DP/USB1_DM)[17]					W	
I <sub>OZ</sub>	OFF-state output current	0 V < V <sub>I</sub> < 3.3 V	[17]	-	-	±10	μA
V <sub>BUS</sub>	bus supply voltage		[18]	-	-	5.25	V
V <sub>DI</sub>	differential input sensitivity voltage	(D+) - (D-)		0.2	-	-	V
V <sub>CM</sub>	differential common mode voltage range	includes V <sub>DI</sub> range		0.8	-	2.5	V
V <sub>th(rs)se</sub>	single-ended receiver switching threshold voltage			0.8	-	2.0	V
V <sub>OL</sub>	LOW-level output voltage for low-/full-speed	$R_L$ of 1.5 k $\Omega$ to 3.6 V		-	-	0.18	V
V <sub>OH</sub>	HIGH-level output voltage (driven) for low-/full-speed	$R_L$ of 15 k $\Omega$ to GND		2.8	-	3.5	V
C <sub>trans</sub>	transceiver capacitance	pin to GND		-	-	20	pF
Z <sub>DRV</sub>	driver output impedance for driver which is not high-speed capable	with 33 $\Omega$ series resistor; steady state drive	<u>[19]</u>	36	-	44.1	Ω

## Table 11. Static characteristics ...continued

 $T_{amb} = -40 \ ^{\circ}C$  to +105  $^{\circ}C$ , unless otherwise specified.

[1] Typical ratings are not guaranteed. The values listed are at room temperature (25 °C), nominal supply voltages.

[2] The recommended operating condition for the battery supply is  $V_{DD(REG)(3V3)} > V_{BAT} + 0.2 V$ . Special conditions for  $V_{DD(REG)(3V3)}$  apply when writing to the flash and EEPROM. See <u>Table 14 and Table 15</u>.

[3] Pin VPP should either be not connected (when OTP does not need to be programmed) or tied to pins VDDIO and VDDREG to ensure the same ramp-up time for both supply voltages.

[4]  $V_{DD(REG)(3V3)} = 3.3 \text{ V}; V_{DD(IO)} = 3.3 \text{ V}; T_{amb} = 25 \text{ °C}.$ 

[5] PLL1 disabled; IRC running; CCLK = 12 MHz.

[6] V<sub>BAT</sub> = 3.6 V.

[7] T<sub>amb</sub> = -40 °C to +105 °C; V<sub>DD(IO)</sub> = V<sub>DDA</sub> = 3.6 V; over entire frequency range CCLK = 12 MHz to 204 MHz; in active mode, sleep mode; deep-sleep mode, power-down mode, and deep power-down mode.

[8] On pin VBAT;  $T_{amb} = 25 \circ C$ .

[9] V<sub>ps</sub> corresponds to the output of the power switch (see <u>Table 9</u>) which is determined by the greater of V<sub>BAT</sub> and V<sub>DD(Reg)(3V3)</sub>.

[10]  $V_{DDA(3V3)} = 3.3 \text{ V}; T_{amb} = 25 \text{ °C}.$ 

[11] Allowed as long as the current limit does not exceed the maximum current allowed by the device.

[12] To V<sub>SS</sub>.

LPC435X 3X 2X 1X

- [13] The values specified are simulated and absolute values.
- [14] The weak pull-up resistor is connected to the  $V_{DD(IO)}$  rail and pulls up the I/O pin to the  $V_{DD(IO)}$  level.
- [15] The input cell disables the weak pull-up resistor when the applied input voltage exceeds  $V_{DD(IO)}$ .

32-bit ARM Cortex-M4/M0 microcontroller

## 10.4 BOD and band gap static characteristics

#### Table 13. BOD static characteristics<sup>[1]</sup>

 $T_{amb} = 25 \ ^{\circ}C$ ; simulated values for nominal processing.

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
V <sub>th</sub>	threshold voltage	interrupt level 2				
		assertion	-	2.95	-	V
		de-assertion	-	3.03	-	V
		interrupt level 3				
		assertion	-	3.05	-	V
		de-assertion	-	3.13	-	V
		reset level 2				
		assertion	-	2.1	-	V
		de-assertion	-	2.18	-	V
		reset level 3				
		assertion	-	2.2	-	V
		de-assertion	-	2.28	-	V

[1] Interrupt and reset levels are selected by writing to the BODLV1/2 bits in the control register CREGE0, see the *LPC43xx user manual*.

#### Table 14. Band gap characteristics

 $V_{DDA(3V3)}$  over specified ranges;  $T_{amb} = -40 \degree C$  to +105  $\degree C$ ; unless otherwise specified

Symbol	Parameter		Min	Тур	Мах	Unit
V <sub>ref(bg)</sub>	band gap reference voltage	[1]	0.707	0.745	0.783	mV

[1] Based on characterization, not tested in production.

32-bit ARM Cortex-M4/M0 microcontroller



## 32-bit ARM Cortex-M4/M0 microcontroller

#### Table 36. Dynamic characteristics: Ethernet

 $T_{amb} = -40$  °C to 105 °C, 2.4 V  $\leq V_{DD(REG)(3V3)} \leq 3.6$  V; 2.7 V  $\leq V_{DD(IO)} \leq 3.6$  V. Values guaranteed by design.

Symbol	Parameter	Conditions		Min	Max	Unit	
RMII moo	de					1	
f <sub>clk</sub>	clock frequency	for ENET_RX_CLK	<u>[1]</u>	-	50	MHz	
$\delta_{\text{clk}}$	clock duty cycle		[1]	50	50	%	
t <sub>su</sub>	set-up time	for ENET_TXDn, ENET_TX_EN, ENET_RXDn, ENET_RX_ER, ENET_RX_DV	[1][2]	4	-	ns	
t <sub>h</sub>	hold time	for ENET_TXDn, ENET_TX_EN, ENET_RXDn, ENET_RX_ER, ENET_RX_DV	<u>[1][2]</u>	2	-	ns	
MII mode	)						
f <sub>clk</sub>	clock frequency	for ENET_TX_CLK	[1]	-	25	MHz	
$\delta_{\text{clk}}$	clock duty cycle		[1]	50	50	%	
t <sub>su</sub>	set-up time	for ENET_TXDn, ENET_TX_EN, ENET_TX_ER	[1][2]	4	-	ns	
t <sub>h</sub>	hold time	for ENET_TXDn, ENET_TX_EN, ENET_TX_ER	<u>[1][2]</u>	2	-	ns	
f <sub>clk</sub>	clock frequency	for ENET_RX_CLK	[1]	-	25	MHz	
$\delta_{\text{clk}}$	clock duty cycle		[1]	50	50	%	
t <sub>su</sub>	set-up time	for ENET_RXDn, ENET_RX_ER, ENET_RX_DV	[1][2]	4	-	ns	
t <sub>h</sub>	hold time	for ENET_RXDn, ENET_RX_ER, ENET_RX_DV	[1][2]	2	-	ns	

[1] Output drivers can drive a load ≥ 25 pF accommodating over 12 inch of PCB trace and the input capacitance of the receiving device.

[2] Timing values are given from the point at which the clock signal waveform crosses 1.4 V to the valid input or output level.



### 32-bit ARM Cortex-M4/M0 microcontroller

On the LPC435x/3x/2x/1x, USBn\_VBUS pins are 5 V tolerant only when VDDIO is applied and at operating voltage level. Therefore, if the USBn\_VBUS function is connected to the USB connector and the device is self-powered, the USBn\_VBUS pins must be protected for situations when VDDIO = 0 V.

If VDDIO is always at operating level while VBUS = 5 V, the USBn\_VBUS pin can be connected directly to the VBUS pin on the USB connector.

For systems where VDDIO can be 0 V and VBUS is directly applied to the USBn\_VBUS pins, precautions must be taken to reduce the voltage to below 3.6 V, which is the maximum allowable voltage on the USBn\_VBUS pins in this case.

One method is to use a voltage divider to connect the USBn\_VBUS pins to VBUS on the USB connector. The voltage divider ratio should be such that the USB\_VBUS pin will be greater than 0.7VDDIO to indicate a logic HIGH while below the 3.6 V allowable maximum voltage.

For the following operating conditions

 $VBUS_{max} = 5.25 V$ VDDIO = 3.6 V,

the voltage divider should provide a reduction of 3.6 V/5.25 V or ~0.686 V.

For bus-powered devices, a regulator powered by USB can provide 3.3 V to VDDIO whenever bus power is present and ensure that power to the USBn\_VBUS pins is always present when the 5 V VBUS signal is applied. See <u>Figure 49</u>.

**Remark:** Applying 5 V to the USBn\_VBUS pins for a short time while the regulator ramps up might compromise the long-term reliability of the part but does not affect its function.



32-bit ARM Cortex-M4/M0 microcontroller

## 15. Soldering



## **NXP Semiconductors**

## LPC435x/3x/2x/1x



Document ID	Release date	Data sheet status	Change notice	Supersedes					
Modifications:		timing data undated. See Tab	lo 25 "Dynamia ak						
Modifications.		dord 902.2 compliance oddar	d to Soction 11 19	Covera Ethernet dynamia					
	characteri	stics of ENET_MDIO and EN	ET_MDC signals.	. Covers Ethemet dynamic					
	<ul> <li>SSP mast 31 "SSP ii</li> </ul>	er mode timing diagram upda n SPI mode and SPI master t	ited with SSEL tim iming".	ning parameters. See Figure					
	<ul> <li>Paramete SPI mode</li> </ul>	rs t <sub>lead</sub> , t <sub>lag</sub> , and t <sub>d</sub> added in Ta ".	able 25 "Dynamic	characteristics: SSP pins in					
	<ul> <li>Parameter t<sub>CSLWEL</sub> with condition PB = 1 corrected: (WAITWEN + 1) × T<sub>cy(clk)</sub> added See Table 29 "Dynamic characteristics: Static asynchronous external memory interface".</li> </ul>								
	<ul> <li>Paramete See Table interface".</li> </ul>	r t <sub>CSLBLSL</sub> with condition PB = 29 "Dynamic characteristics:	0 corrected: (WA Static asynchrono	$TWEN + 1) \times T_{cy(clk)}$ added.					
	Removed	<ul> <li>Removed restriction on C_CAN bus usage. See CAN.1 errata in Ref. 2.</li> </ul>							
	<ul> <li>General-p</li> </ul>	urpose OTP size corrected.							
LPC435X_3X_2X_1X v.3	20121206	Preliminary data sheet	-	LPC4357_53_37_33 v.2.1					
Modifications:	TFBGA18	0 packages removed.	I	I					
	Part LPC4	32x and LPC431x added.							
	SCT dithe	r engine added and SCT bi-d	irectional event er	nable features added.					
	Figure 10	"Dual-core debug configuration	on" added.						
	• T = 105 °C	C data added in Figure 20 to I	Figure 23.						
	Change s	mbol names and parameter	names in Table 2'	1.					
	Paramete	r $I_{IH}$ updated for condition $V_{I}$	= 5 V and $T_{amb}$ =	25 °C/105 °C in Table 11.					
	<ul> <li>Power cor</li> </ul>	nsumption data added in Sect	tion 10.1.						
	SPIFI dvn	amic characteristics added in	Section 11.16.						
	IRC accur	acv corrected to $\pm 2$ % for T <sub>an</sub>	<sub>ob</sub> = -40 °C to 0 °C	and $T_{amb} = 85 \text{ °C to } 105 \text{ °C}$ .					
	<ul> <li>Pull-up an</li> <li>T<sub>amb</sub> = 10</li> </ul>	d Pull-down current data (Fig 5 °C.	ure 24 and Figure	25) updated with data for					
	SPIFL max	cimum data rate changed to 5	2 MB per second						
	Recomme battery su	endation for $V_{BAT}$ use added:	The recommende	d operating condition for the					
	<ul> <li>Table 14 "</li> </ul>	Band dap characteristics" add	ded						
	<ul> <li>Section 7.</li> </ul>	23.9 "Power Management Co	ontroller (PMC)" a	dded.					
	Descriptio     is connect	n of ADC pins on digital/analoged to ADC0 and ADC1. See	og input pins chan	ged. Each input to the ADC					
	OTP mem	ory size changed to 64 bit							
	• Use of C	CAN peripheral restricted in S	Section 2						
	ADC char	inels limited to a total of 8 cha	annels shared bet	ween ADC0 and ADC1					
LPC4357 53 37 33 v 2 1	20120904	Preliminary data sheet							
Modifications:	<ul> <li>SSP0 boo</li> <li>B2 6 - S2</li> </ul>	t pin functions corrected in Ta	ble 5 and Table 4.	Pin P3_3 = SSP0_SCK, pin					
	$F_{3} = 33$	$510_33EL, pill F3_7 = 35P0$	_wii30, piii F3_0						
		oven for Artivi Collex-IVIU.	13						
	DOD ue-a      Derinhera	social and the second	ted in Table 12						
			bongod to $0.5.1$	in Tabla 7					
	<ul> <li>iviinimum</li> </ul>	value for all supply voltages o	manged to -0.5 V						

Table 47. Revision history ... continued

#### 32-bit ARM Cortex-M4/M0 microcontroller

**Export control** — This document as well as the item(s) described herein may be subject to export control regulations. Export might require a prior authorization from competent authorities.

Non-automotive qualified products — Unless this data sheet expressly states that this specific NXP Semiconductors product is automotive qualified, the product is not suitable for automotive use. It is neither qualified nor tested in accordance with automotive testing or application requirements. NXP Semiconductors accepts no liability for inclusion and/or use of non-automotive qualified products in automotive equipment or applications.

In the event that customer uses the product for design-in and use in automotive applications to automotive specifications and standards, customer (a) shall use the product without NXP Semiconductors' warranty of the product for such automotive applications, use and specifications, and (b)

## 20. Contact information

whenever customer uses the product for automotive applications beyond NXP Semiconductors' specifications such use shall be solely at customer's own risk, and (c) customer fully indemnifies NXP Semiconductors for any liability, damages or failed product claims resulting from customer design and use of the product for automotive applications beyond NXP Semiconductors' standard warranty and NXP Semiconductors' product specifications.

## 19.4 Trademarks

Notice: All referenced brands, product names, service names and trademarks are the property of their respective owners.

I<sup>2</sup>C-bus — logo is a trademark of NXP B.V.

For more information, please visit: <u>http://www.nxp.com</u>

For sales office addresses, please send an email to: salesaddresses@nxp.com

LPC435X\_3X\_2X\_1X

© NXP Semiconductors N.V. 2016. All rights reserved.